

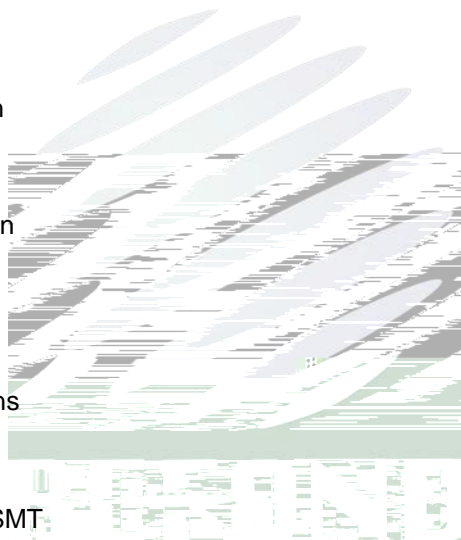


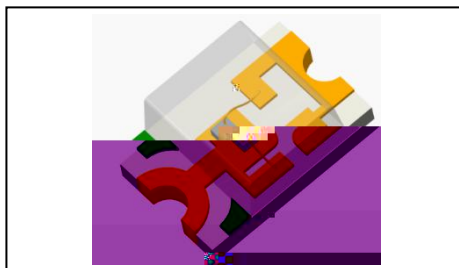
REFOND P/N
RF-TUR150TS-CE-E2

Mass Product

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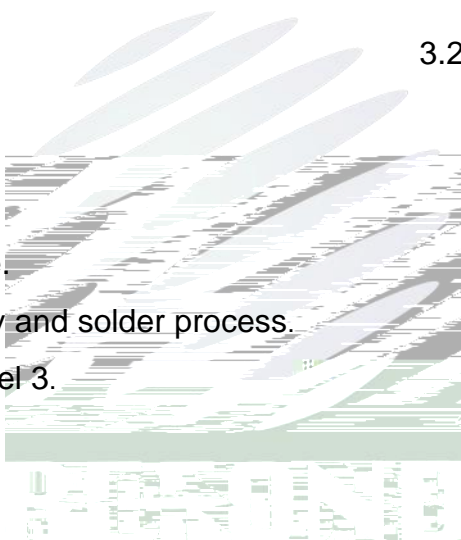




The Colour LED which was fabricated using a green chip Package Dimension :
3.2mmX1.25mmX1.1mm.

LED

3.2mmX1.25mmX1.1mm



Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Moisture sensitivity level: Level 3.

RoHS compliant.

Optical indicator.

Switch and symbol, display.

General use.

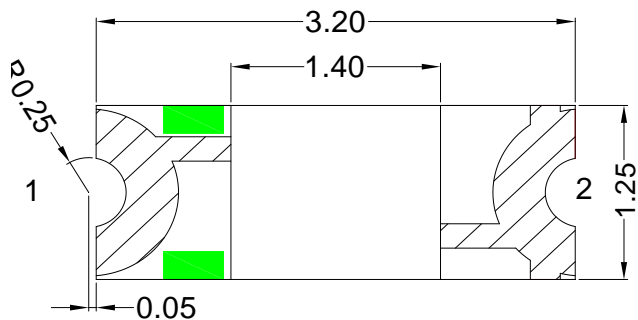


Fig.1-1 Top view

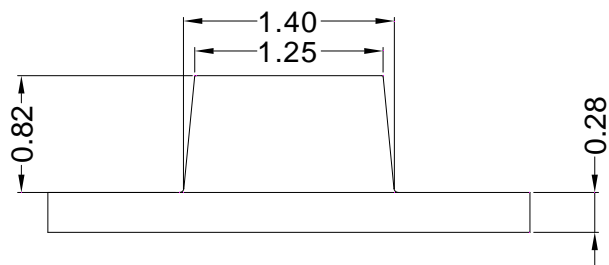


Fig.1-2 Side view

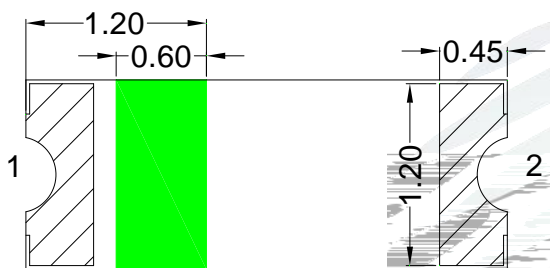


Fig.1-3 Bottom view

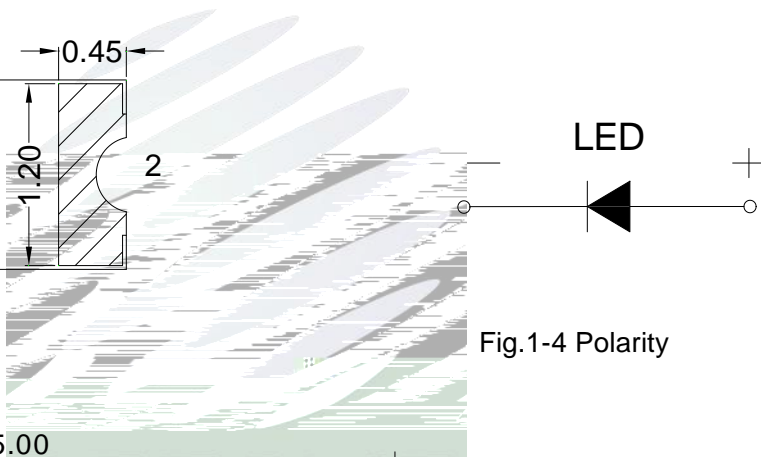


Fig.1-4 Polarity

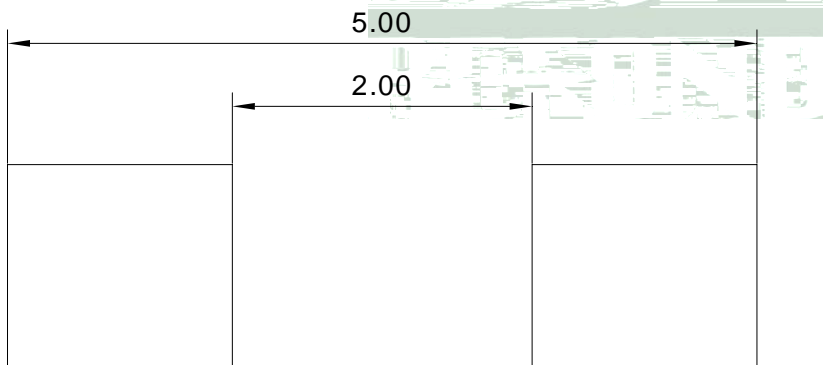


Fig.1-5 Soldering patterns

Notes

All dimensions units are millimeters.

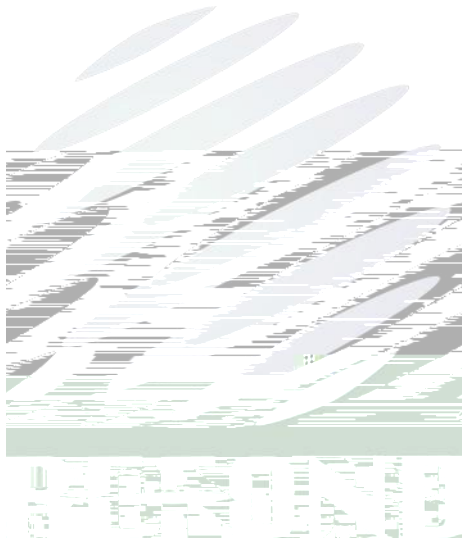
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Test Condition	Symbol		Value			Unit
				Min. ()	Typ.	Max.	
Spectral Half Bandwidth	I _F =20mA			--	30	--	nm
Forward Voltage	I _F =20mA	V _F	G1	2.8	--	2.9	V
			G2	2.9	--	3.0	V
			H1	3.0	--	3.1	V
			H2	3.1	--	3.2	V
			I1	3.2	--	3.3	V
			I2	3.3	--	3.4	V
			J1	3.4	--	3.5	V
Dominant Wavelength	I _F =20mA	D	D20	517.5	--	520	nm
			E10	520	--	522.5	nm
			E20	522.5	--	525	nm
			F10	525	--	527.5	nm
			F20	527.5	--	530	nm
Luminous Intensity	I _F =20mA	I _v	1AU	260	--	330	mcd
			1AV	330	--	430	mcd
			1CG	430	--	560	mcd
			1CL	560	--	700	mcd
			1CM	700	--	900	mcd
Viewing Angle	I _F =20mA	2 1/2		--	140	--	deg
Reverse Current	V _R =5V	I _R		--	--	10	μA
Thermal Resistance.	I _F =20mA	R _{THJ-S}		--	--	450	/W

 Notes : V_R=5V For test conditions. V_R=5V

Table 1-2 Absol



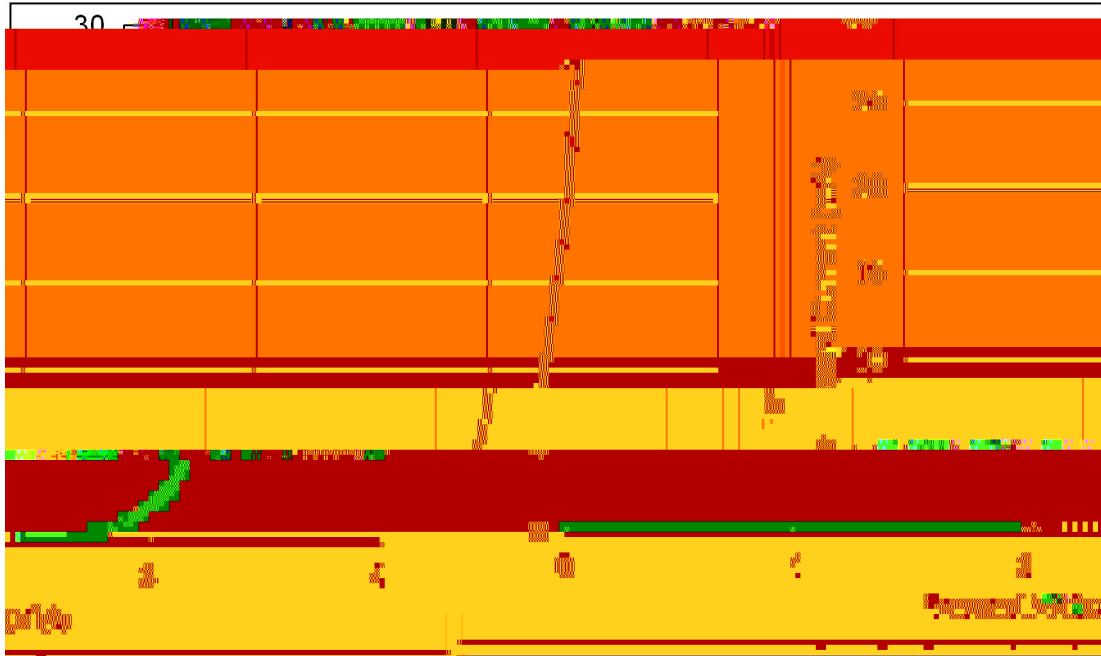


Fig 1-6 Forward Voltage Vs Forward Current

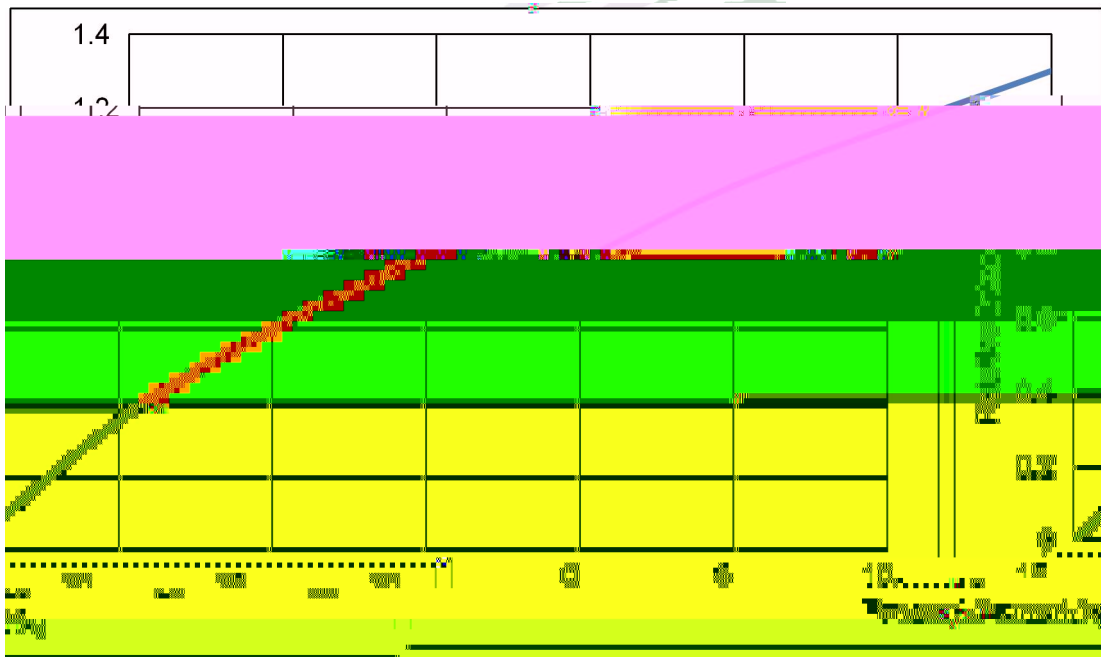


Fig 1-7 Forward Current Vs Relative Intensity

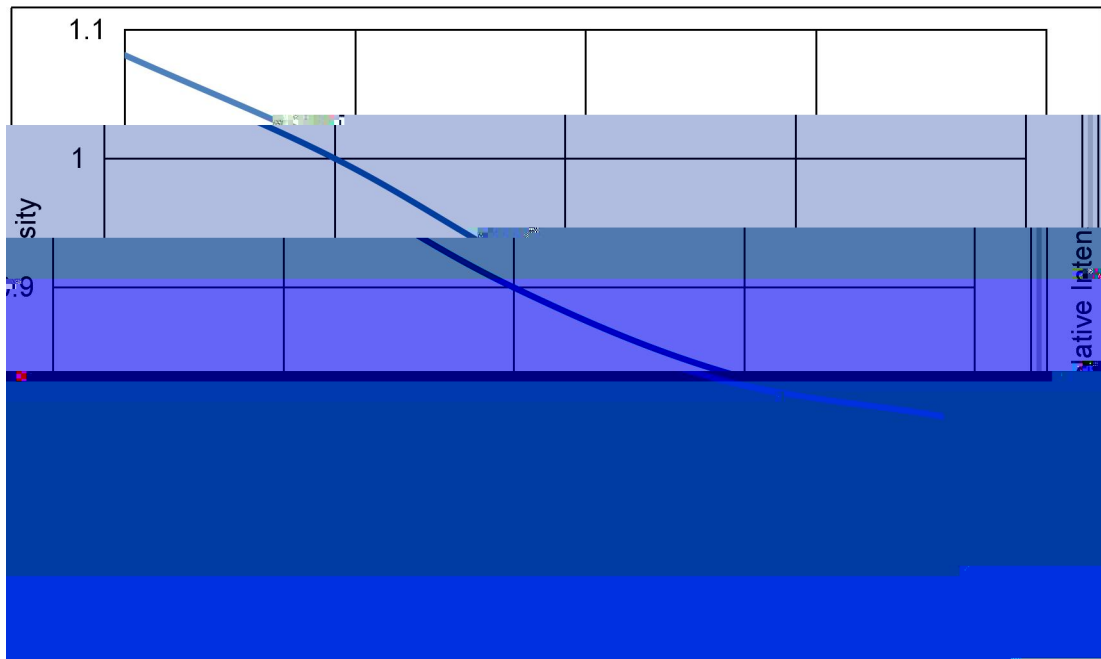


Fig 1-8 Pin Temperature Vs Relative Intensity

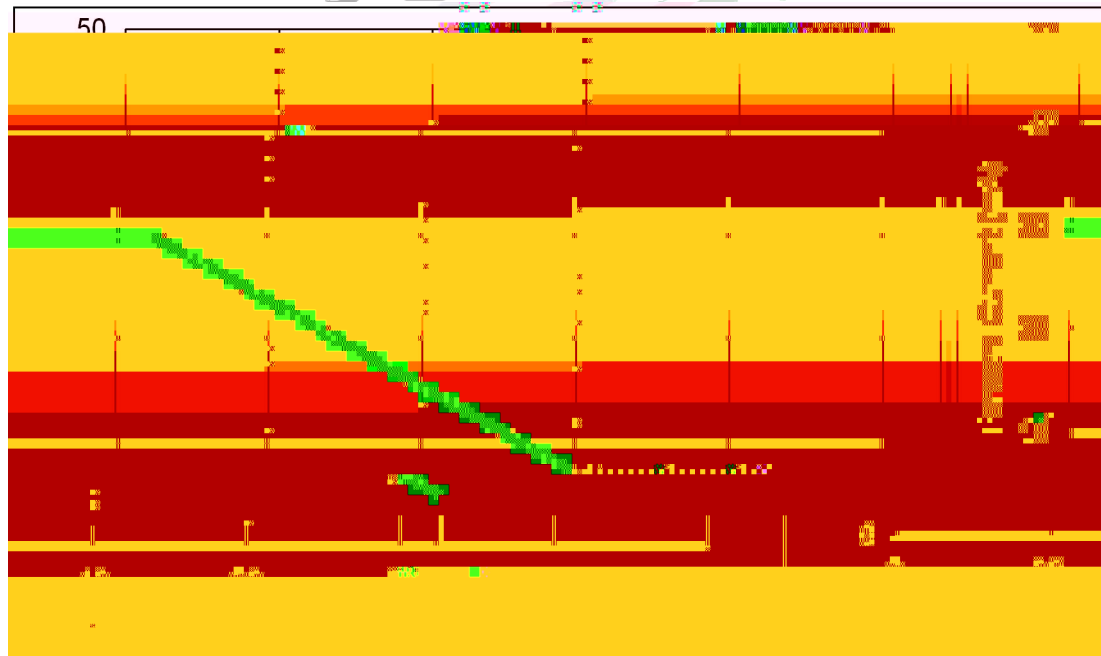


Fig 1-9 Pin Temperature Vs Forward Current

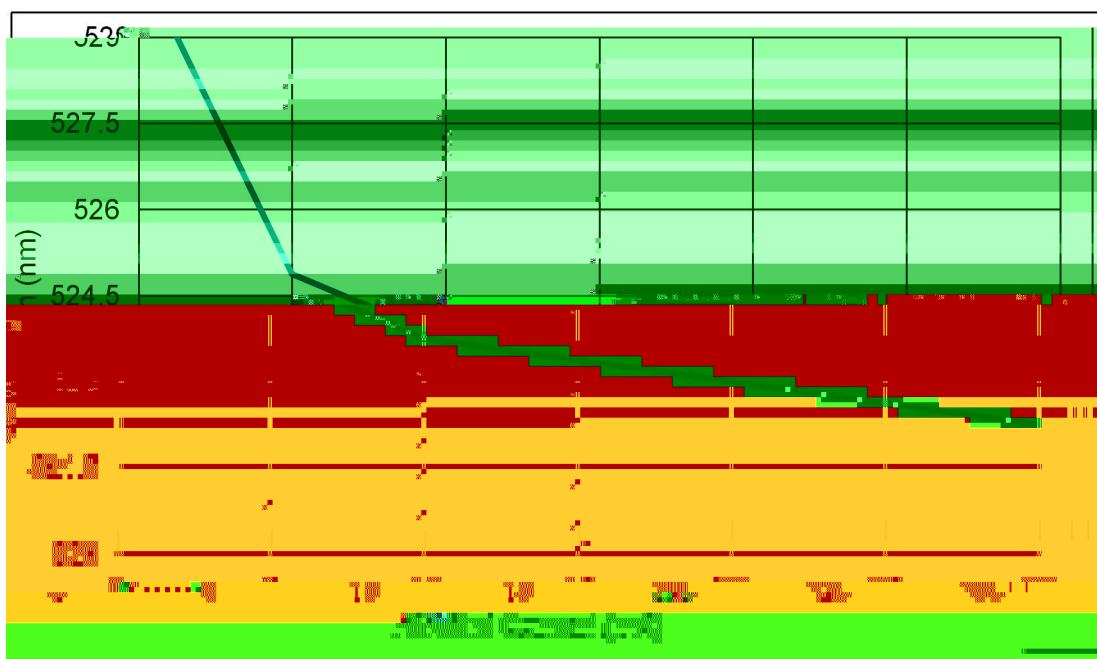


Fig 1-10 Forward Current Vs Dominate Wavelength (Ta=25)

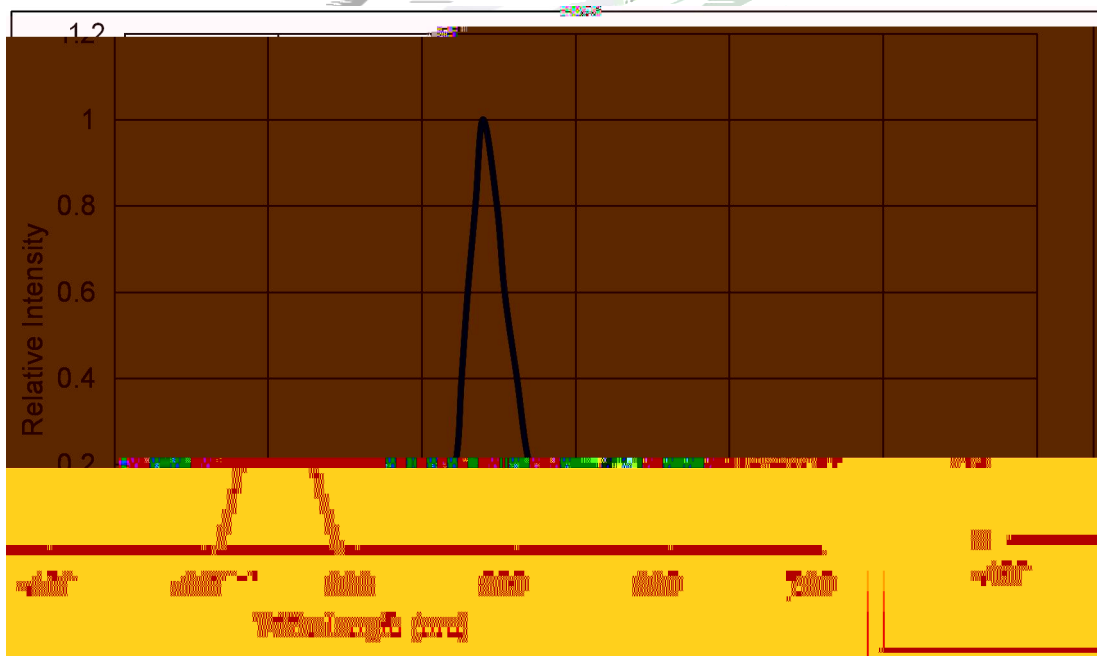
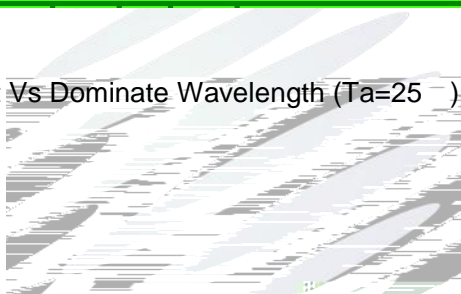


Fig 1-11 Relative Intensity Vs Wavelength (Ta=25)

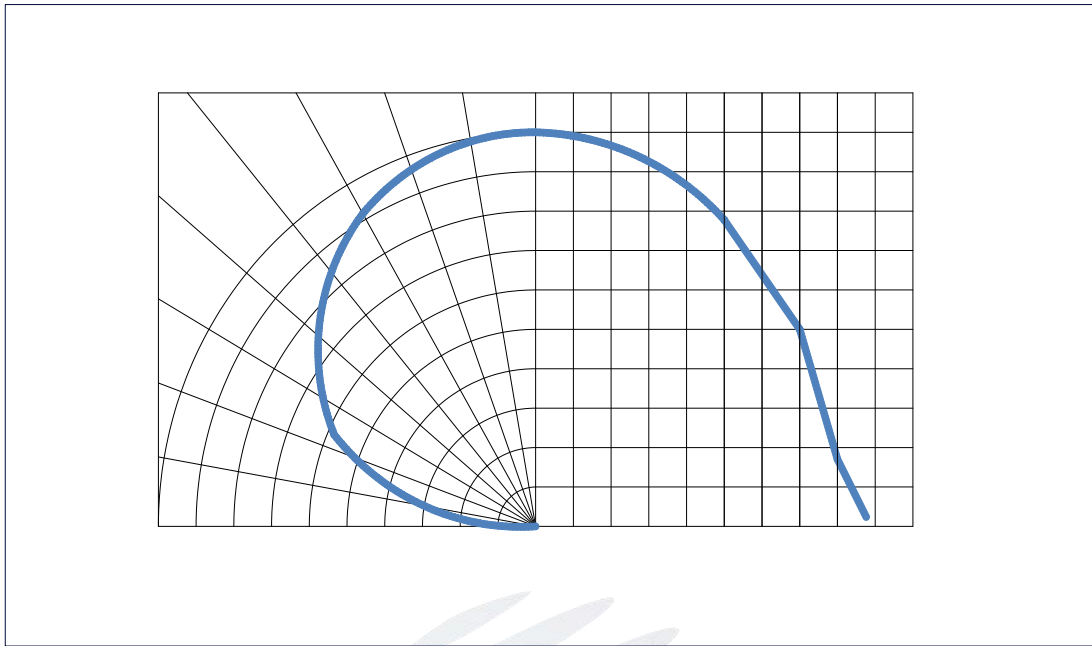


Fig 1-12 Diagram characteristics of radiation



Package:3000pcs/reel. 3000pcs

2.1.1 Carrier Tape Dimension

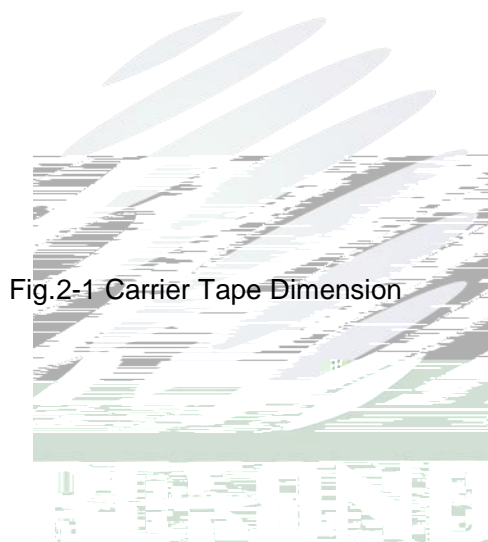


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

Table 2-1 Dimension

A	8.0	0.1mm
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Fig.2-2 Reel Dimension

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm

2.1.3 Label Form Specification

Table 2-2 Parameter

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

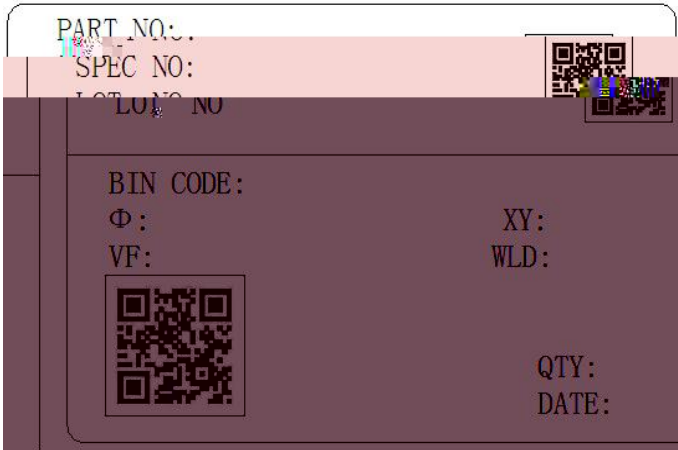


Fig. 2-3 Label Form Specification



Fig.2-4 Moisture Resistant Packing

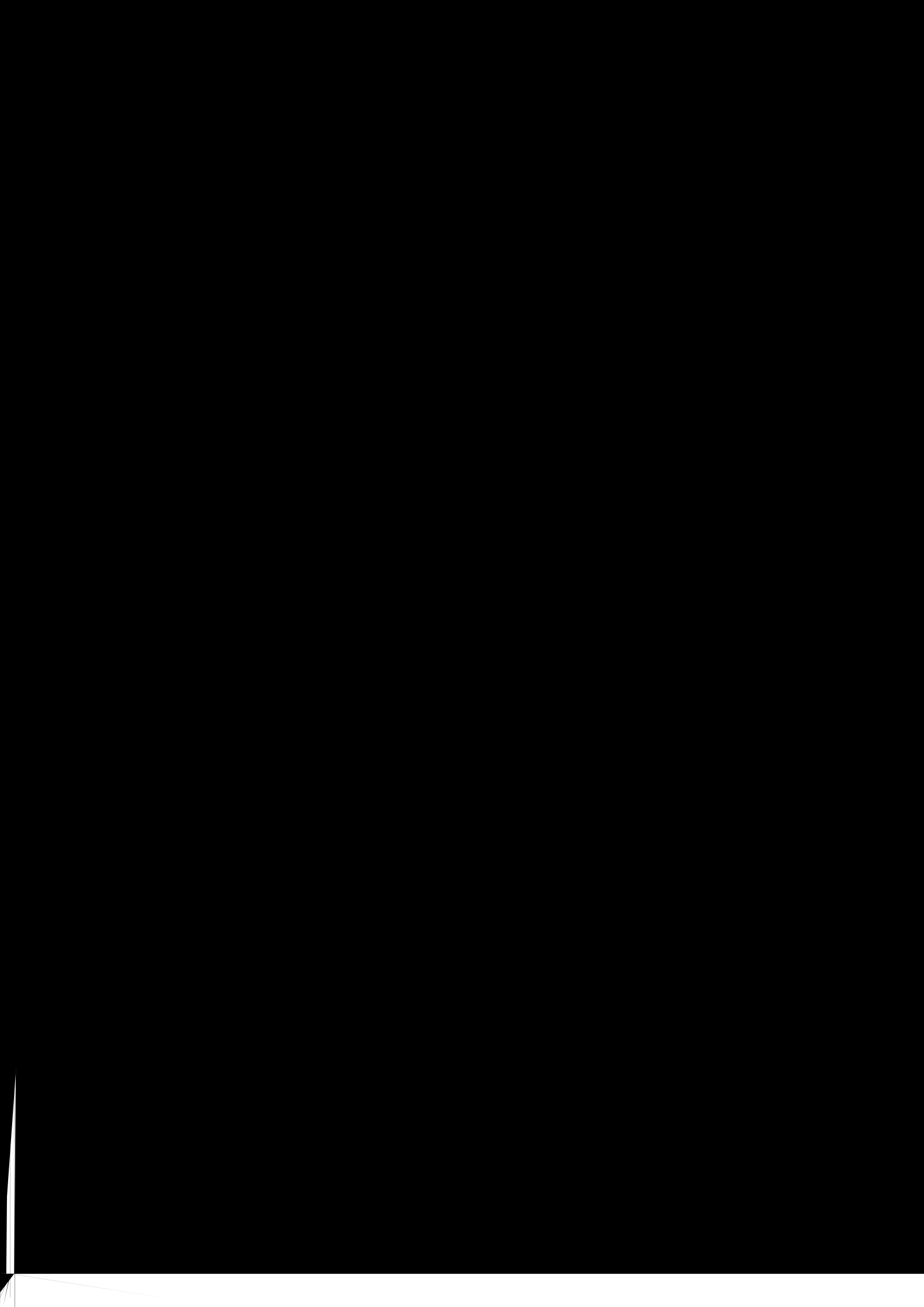


Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=20mA$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R= 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=20mA$	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level

L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. When customers applies the LED to the series and parallel circuit,should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Parameter

Average temperature rise speed	T_{smax}	T_P	3 °C/	Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})		150 °C	
Preheating: Max temperature	(T_{smax})		200 °C	
Preheating: Time	T_{smin}	T_{smax}	60 - 120	60s0

Notes

(1) Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings, LED will be damaged.

(2) When soldering, do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

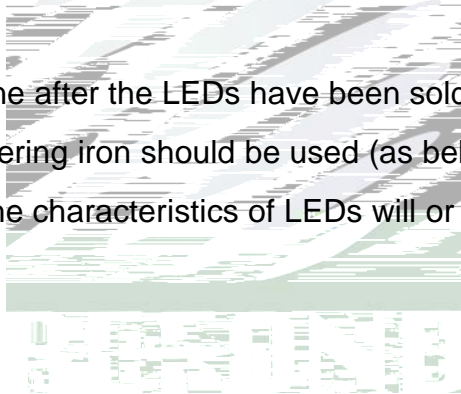
(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED



3.1.3 Cautions

(1) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED

(2) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.



(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of selected fixtures in construction can of

(4) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(5) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(6) Storage



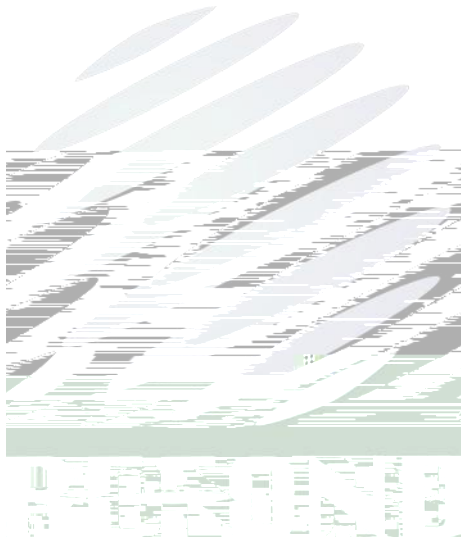
Conditions		Temperature	Humidity	Time
Storage	Before Opening Alum Bag	30	75%	Within 1 Year From Date
	After Opening Alum Bag	30	60%	1688 hours 168
Baking		60	-	24 hours 24

(7) If the moisture absorbent material silica has faded away or the LEDs have exceeded the storage time baking treatment should be performed after unpacking and based on the following condition 60±5 for above 24 hours.

If the package is flatulence or damaged, please notify the sales staff to assist.

(8) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(9) Other points for attention, please refer to our relevant information.





Declare

This specification is written both in English and in Chinese and the latter is formal.